

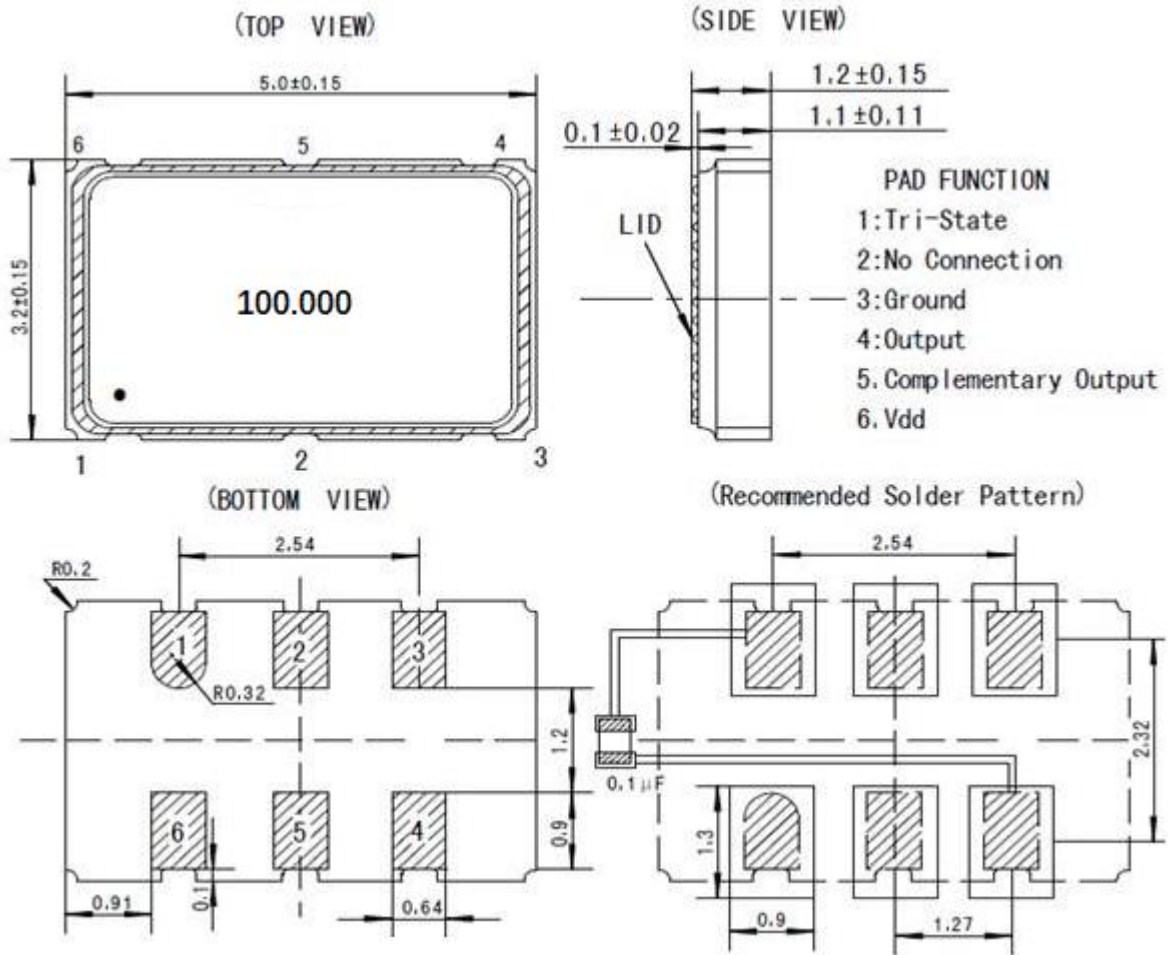


1、 Electrical Parameters

| MODEL: DPCE100M0001 | | | | | | | |
|---------------------|---------------------------|--|------------------|------|---------|------------------|--|
| No. | Parameters | SYM. | Electrical Spec. | | | | Notes |
| | | | Min. | Typ. | Max. | Units | |
| 1 | Nominal Frequency | FL | 100.000 | | | MHz | |
| 2 | Vibration Mode | - | 3rd | | | | |
| 3 | Output Waveform | - | LVDS | | | | |
| 4 | Total stability | F-stab | -25 | | +25 | $\times 10^{-6}$ | Include frequency tolerance@25°C and frequency stability vs. operating temperature range and voltage variance. |
| 5 | Operating Temperature | - | -40 | 25 | 85 | °C | |
| 6 | Storage temperature range | - | -55 | | 125 | °C | |
| 7 | Operating Supply Voltage | Vdd | 2.97 | 3.3 | 3.63 | V | |
| 8 | “H” Output voltage | VOH | | | 1.6 | V | 100±1 Ω (R1+R1 between OUT-OUTN) |
| 9 | “L” Output voltage | VOL | 0.9 | | | V | |
| 10 | Max Supply Voltage Range | - | -0.5 | | 5 | V | |
| 11 | Supply Current | Icc | | | 40 | mA | |
| 12 | Start up Time | - | | | 10 | mS | |
| 13 | Rise and Fall Time | Tr/Tf | | | 0.5 | nS | @20%-80% |
| 14 | Duty Cycle | - | 45 | | 55 | % | @Vcc-1.3V |
| 15 | Aging | - | -3 | | +3 | $\times 10^{-6}$ | 1year@25°C |
| 16 | Jitter | RMS | | | 0.2 | ps | 12kHz ~ 20MHz |
| 17 | Phase Noise | | | | -60 | dBc | 10Hz |
| | | | | | -95 | dBc | 100Hz |
| | | | | | -120 | dBc | 1KHz |
| | | | | | -135 | dBc | 10KHz |
| | | | | | -143 | dBc | 100KHz |
| | | | | | -148 | dBc | 1MHz |
| 18 | Enable Feature | | | | | | |
| 19 | “H” Input Voltage | VIH | Vcc*0.7 | | | V | |
| 20 | “L” Input Voltage | VIL | | | Vcc*0.3 | V | |
| 21 | E/D (Pin 1) | Logic “1”Or Floating input, Outputs enable; Logic “0” ,Outputs disable | | | | | |

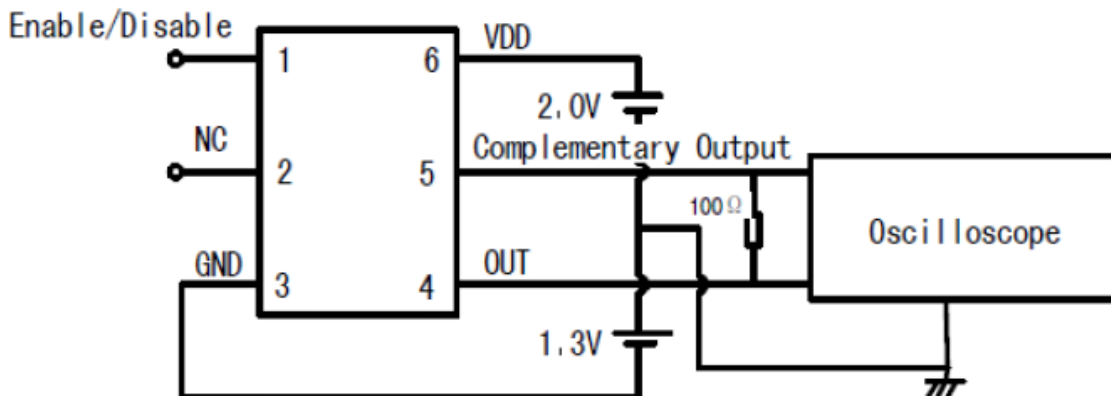


2、Mechanical Structure(mm)



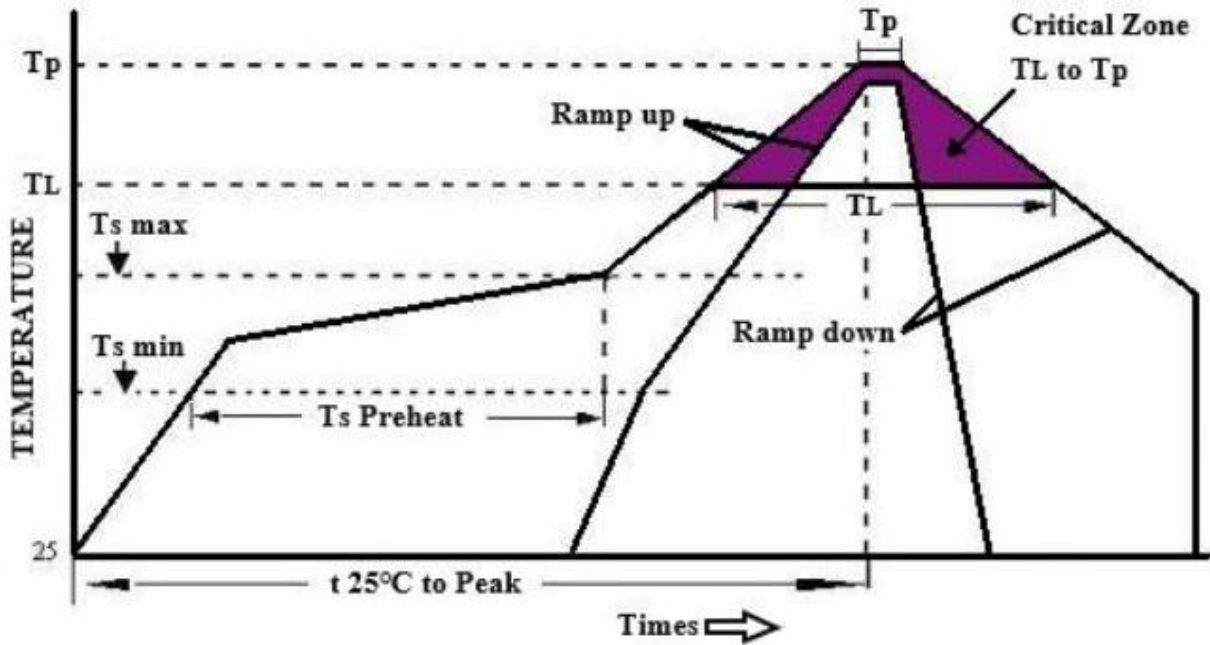
Note1: Tolerance ±0.2 mm

3. Test Circuit





4. Reflow Soldering Curve (RoHS)



High Temperature Infrared /Convection

Note:Temperature shown are applied to body of device

| | |
|---|--------------------------|
| Ts max to TL(Ramp-up Rate) | 3°C/second max |
| Preheat | |
| Temperature Min(Ts Min) | 150°C |
| Temperature Typical(Ts Typ) | 175°C |
| Temperature Max.(Ts Max) | 200°C |
| Time(ts) | 60-180 seconds |
| Ram-up Rate(T _L to T _p) | 3°C/second Max |
| Time Maintained Above: | |
| --Temperature(T _L) | 217°C |
| --Time(T _L) | 60-150seconds |
| Peak Temperature (T _p) | 260°C Max for 10 seconds |
| Time within 5°C of actual peak(t _p) | 20-40 seconds |
| Ramp-down Rate | 6°C/seconds Max |
| Tune 25°C to Peak Temperature(t) | 8 minutes Max |
| Moisture Sensitivity Level | Level 1 |

High Temperature Manual Soldering

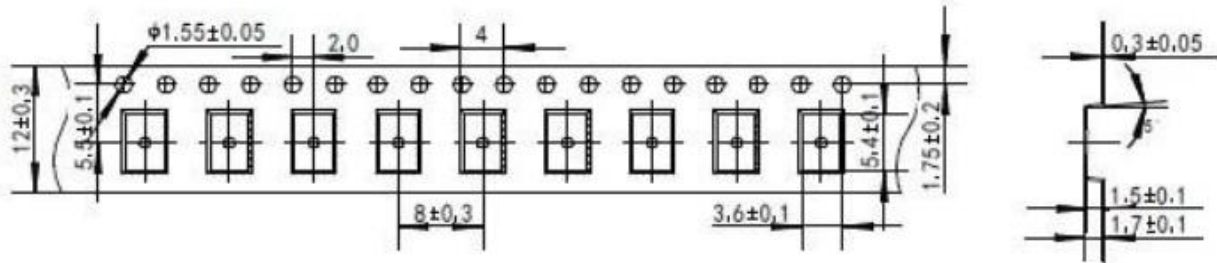
Note:Temperature shown are applied to body of device

260°C Max for 10 seconds Max. 4 times Max

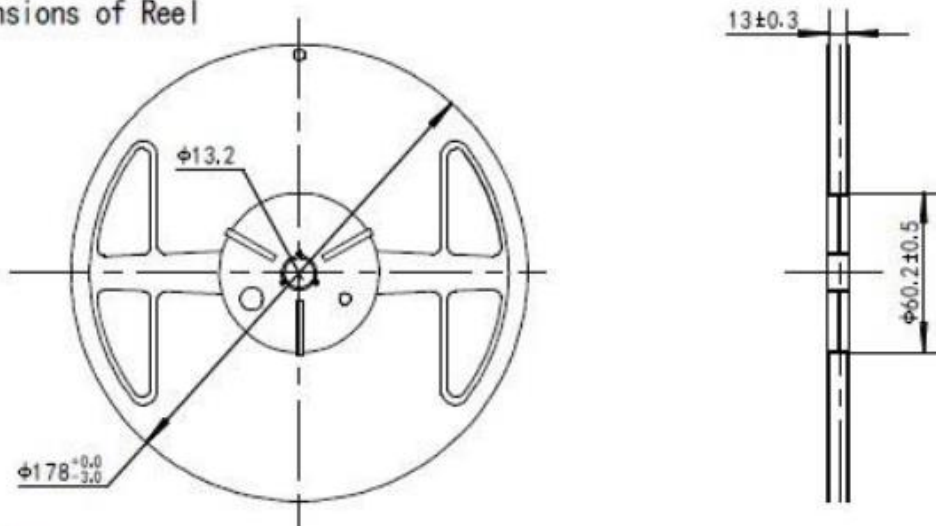


5. Package: Tape & Reel (mm)

1. Dimensions of Carrier Tape



2. Dimensions of Reel



3. Packing

1 reel/box 1 reel=1000pcs

10 boxes/carton(the carton with bubble pad on four sides)

